

WHAT IS CLAIMED IS:

1. An improved structure of gold fingers, built in a stacked-chip packaging structure, and the stacked-chip packaging structure includes a plurality of stacked chips, and each chip has a plurality of wires that
5 is connected to a plurality of gold finger sets, wherein each gold finger set has a plurality of gold finger units that are electrically connected to one another, and each wire that can be connected to one another on each chip is connected to the gold finger unit of the same gold finger set.
- 10 2. The improved structure of gold fingers as claimed in claim 1, wherein each wire that can be connected to one another on each chip is separately connected to different gold finger units of the same gold finger set.
3. The improved structure of gold fingers as claimed in claim 2, wherein
15 the number of the gold finger units is not less than the number of the chips.
4. The improved structure of gold fingers as claimed in claim 1, wherein on some part of the chips, each wire that can be directly connected to one another is connected to the same gold finger unit of the same gold
20 finger set.
5. The improved structure of gold fingers as claimed in claim 1, wherein between each gold finger unit, there is at least one wire to connect the gold finger unit so as to form electrical connection.
6. The improved structure of gold fingers as claimed in claim 4, wherein a

solder resist layer covers the wire.

7. The improved structure of gold fingers as claimed in claim 1, wherein the gold finger set can be a complete gold finger, and at least one solder resist layer covers a part of the surface of the complete gold finger so
- 5 as to divide it into a plurality of gold finger units.